



Southern
New Hampshire
University

School of Engineering,
Technology, and Aeronautics

Critical Design Review

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TEAM
THERMOCLINE

Project Team & Roles



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Agenda

- Overview
- Requirements Compliance
- Subsystems
 - Structural
 - Thermal-Fluid
 - Electrical
 - Control System
 - Safety
- Budget
- Open Design Items
- Data Acceptance Package Status



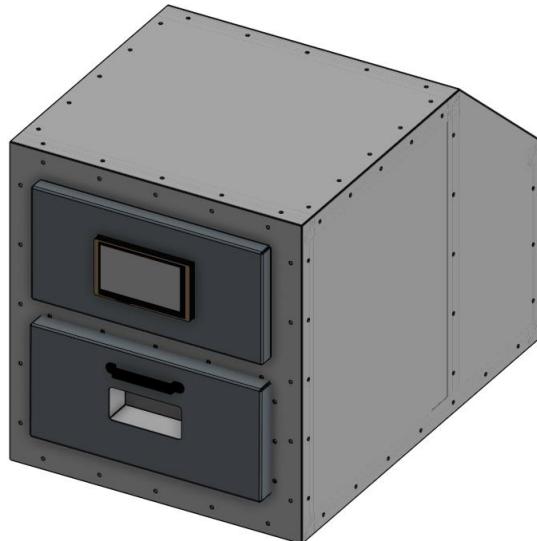
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Context

- Thermally-controlled Printed Circuit Board (“PCB”) testing chamber
 - Table-top system
 - User-control & automatic operation
 - Spanning 0°C – 70°C commercial temperature range
- Purpose: evaluating operation, functionality, & performance of electronic components in an enclosure replicating environmental conditions.



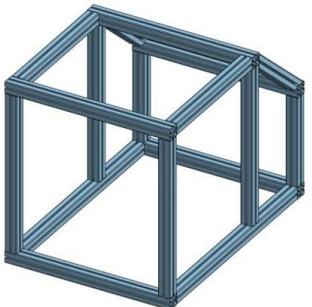
Requirements Compliance

Req. Num	Short Desc.	Status	Margin
STR-01	System Bounds	Current CAD and footprint overall fit in our maximum size.	10%
STR-03	Insulation and seal	Minimum thicknesses for insulation are within our requirements	<5%
THE-01	Min. Temperature	Pre-modification system reached 0, r410 boils at -43.	50%
THE-02	Sweep Speed	Heat rejection is 2-3 times larger than evaporator requirement	35%
CON-08	Log faults	RTOS logging setup as part of underlying structure	Met
SAF-05	Have a safe state	Implemented in underlying structure	Met

System Design

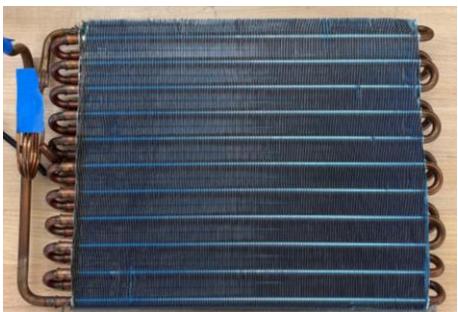
Holistic System

Structural



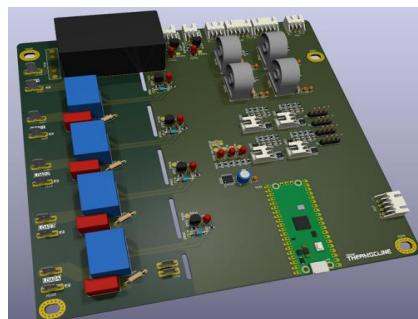
1.1 - The system shall accommodate a 12x12" PCB as a device to be tested.

Thermal-fluid



2.1.1 - The PCB shall be interfaceable while the system is running.

Electrical



3.2.1 - The system shall cover commercial temperature range (0-70°C)

Control System



3.2.4 - The system shall maintain a temperature $\pm 3^\circ\text{C}$ of setpoint.

Safety



3.4.5 - The system shall be capable of sweeping the temperature range in a 24-hour cycle.

Subsystem Design: Structural

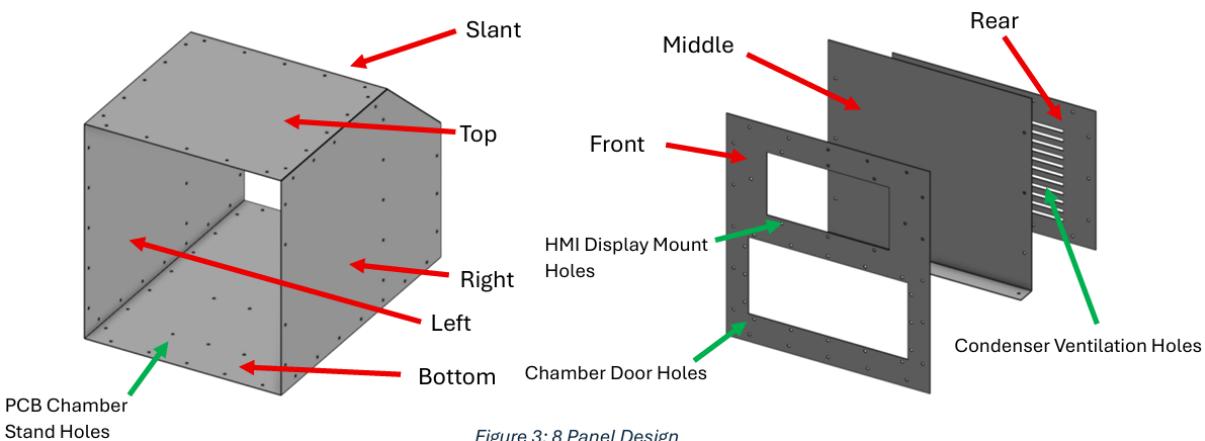
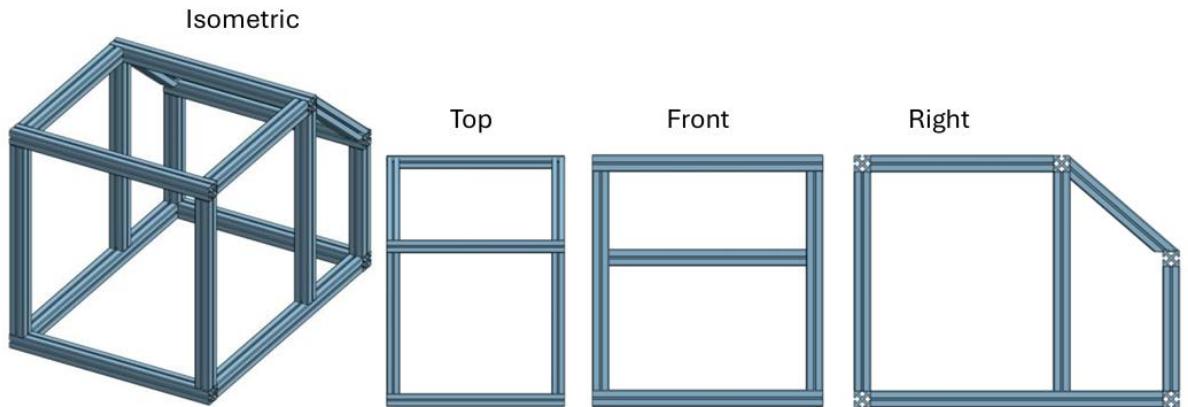


Figure 3: 8 Panel Design

Driving Requirements:

- **STR-01:** The system shall have external base dimensions of no more than 30x30 inches.
- **STR-03:** The chamber opening(s) shall include proper thermal sealing according to ASTM F1886.

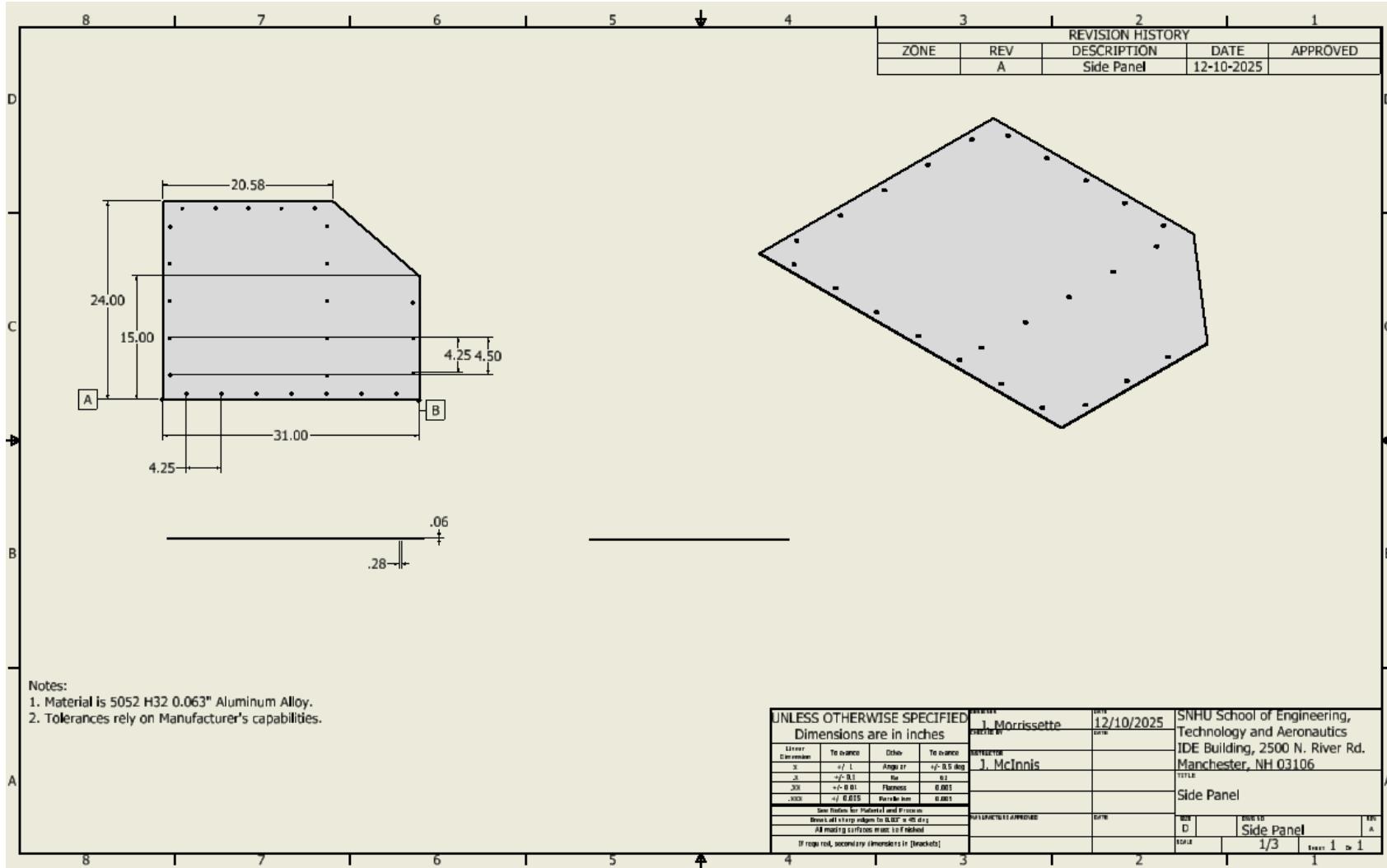


Onshape Link (View Only)

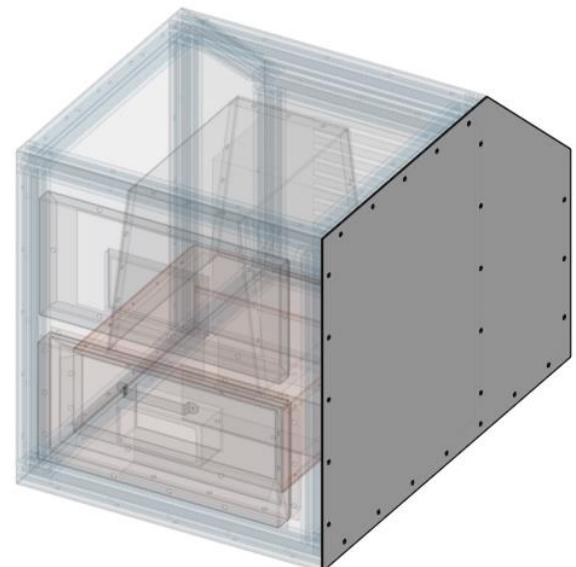


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Subsystem Design: Structural

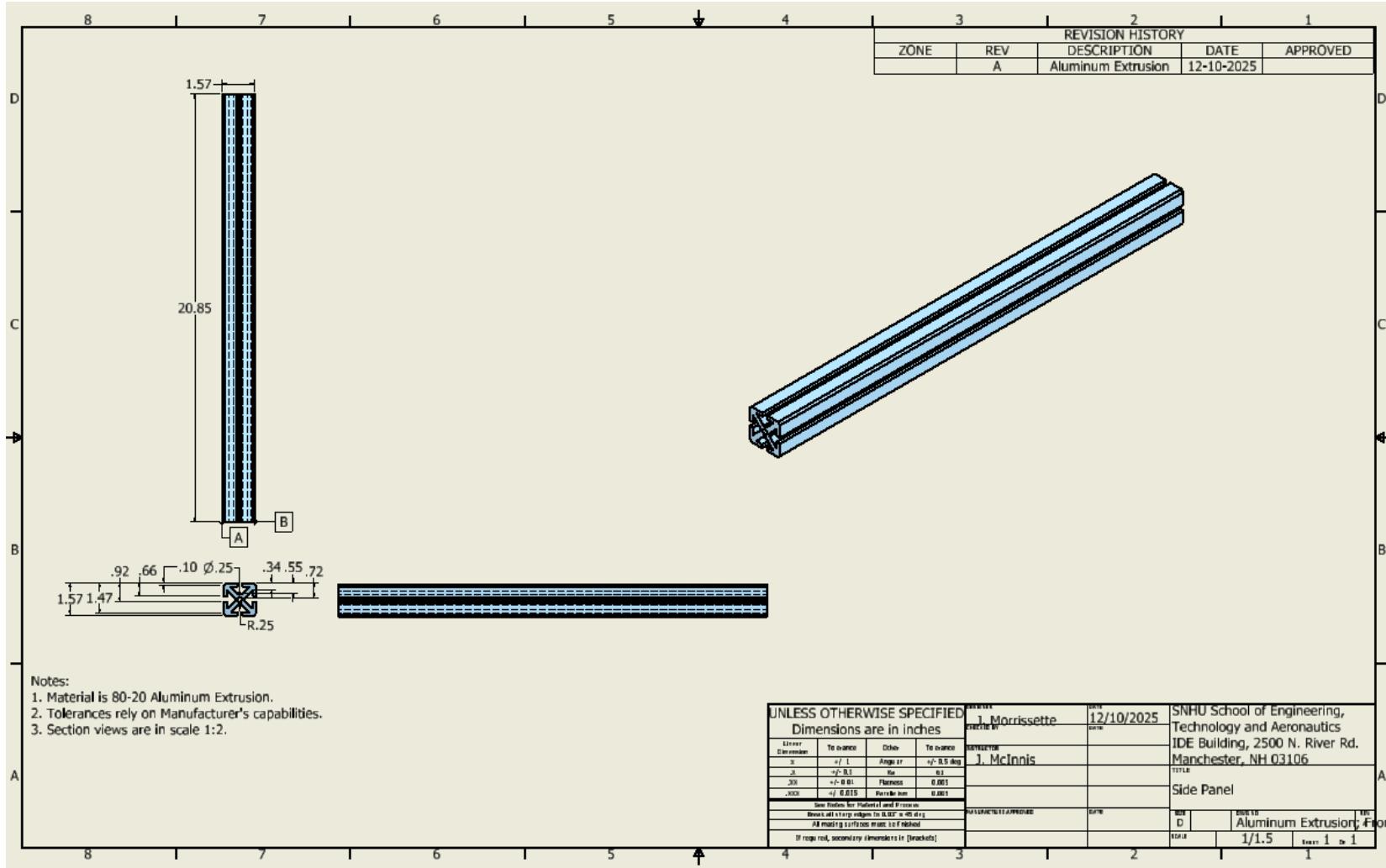


External Side Panel

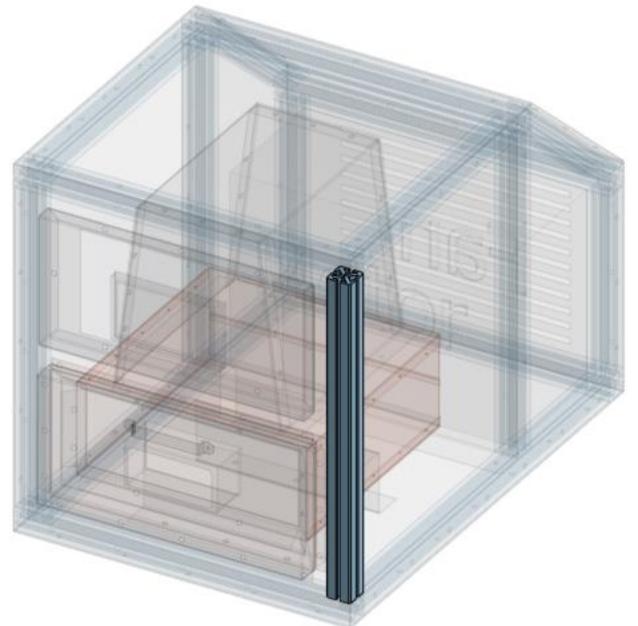


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Subsystem Design: Structural



Aluminum Extrusion Frame



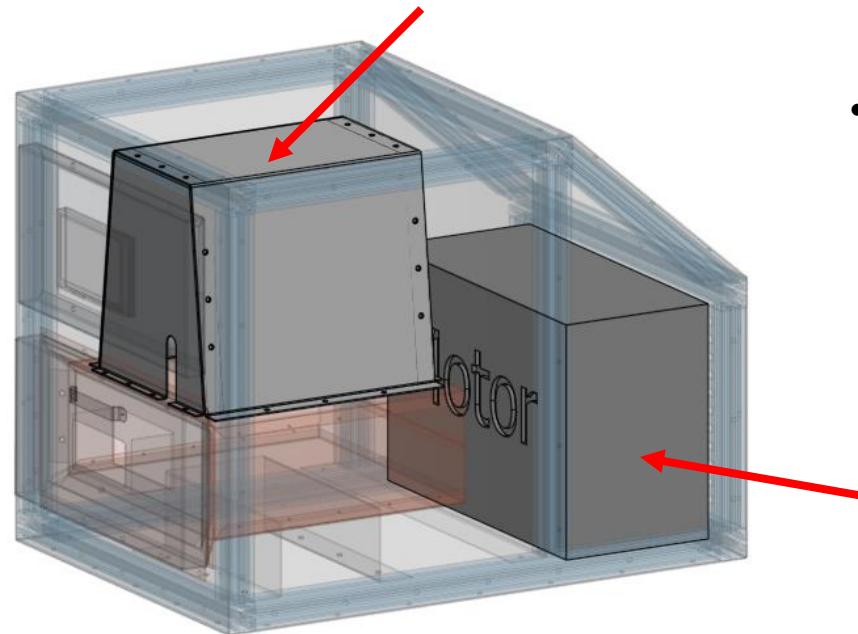
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Subsystem Design: Thermo-fluid



R410a Recovery Tank

Airflow Management Chamber
(Heater, Evaporator, & Fan)



Driving Requirements:

- **THE-01:** The system shall cover *commercial* temperature range (0°C - 70°C).
- **THE-02:** The system shall be capable of sweeping all temperature ranges within a 24-hour cycle.

Heat Outlet Chamber
(Condenser & Fan)



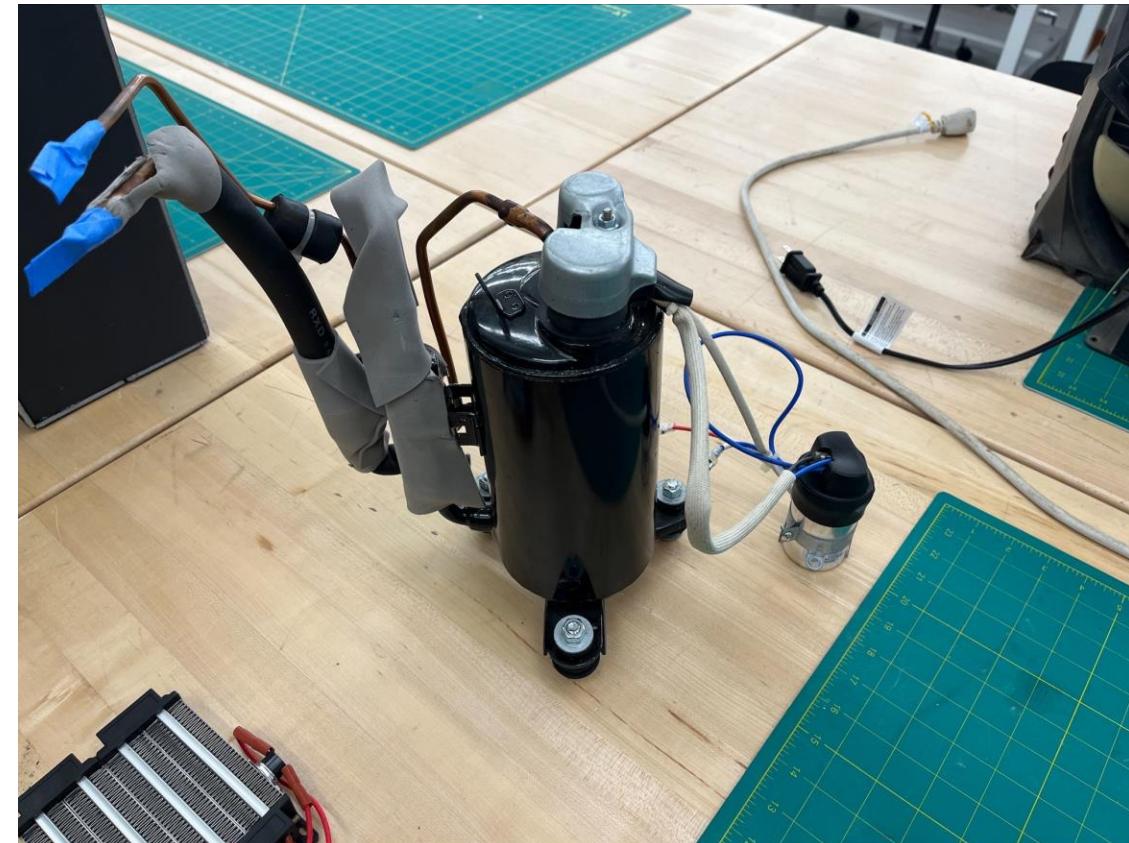
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Subsystem Design: Thermo-fluid

We tested our compressor prior to disassembly for verification of our minimum performance requirements.

- **Results:**

- Condenser Temperature: 0°C (< 30min until steady) 
- Compressor Temperature: 74°C (< 30min until steady) 
- Current Draw: 5A (~ 2s until steady)

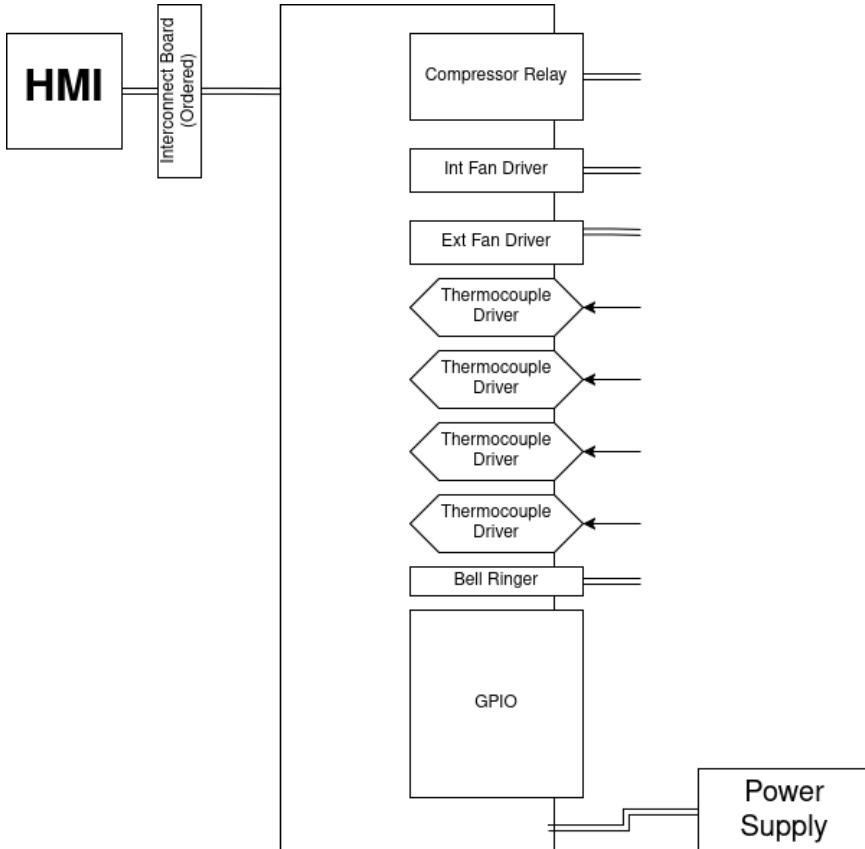


Mechanical compressor



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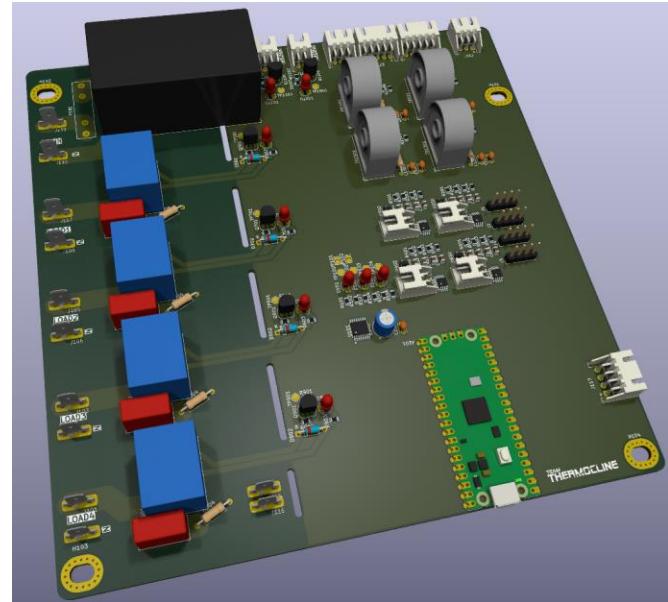
Subsystem Design: Electrical



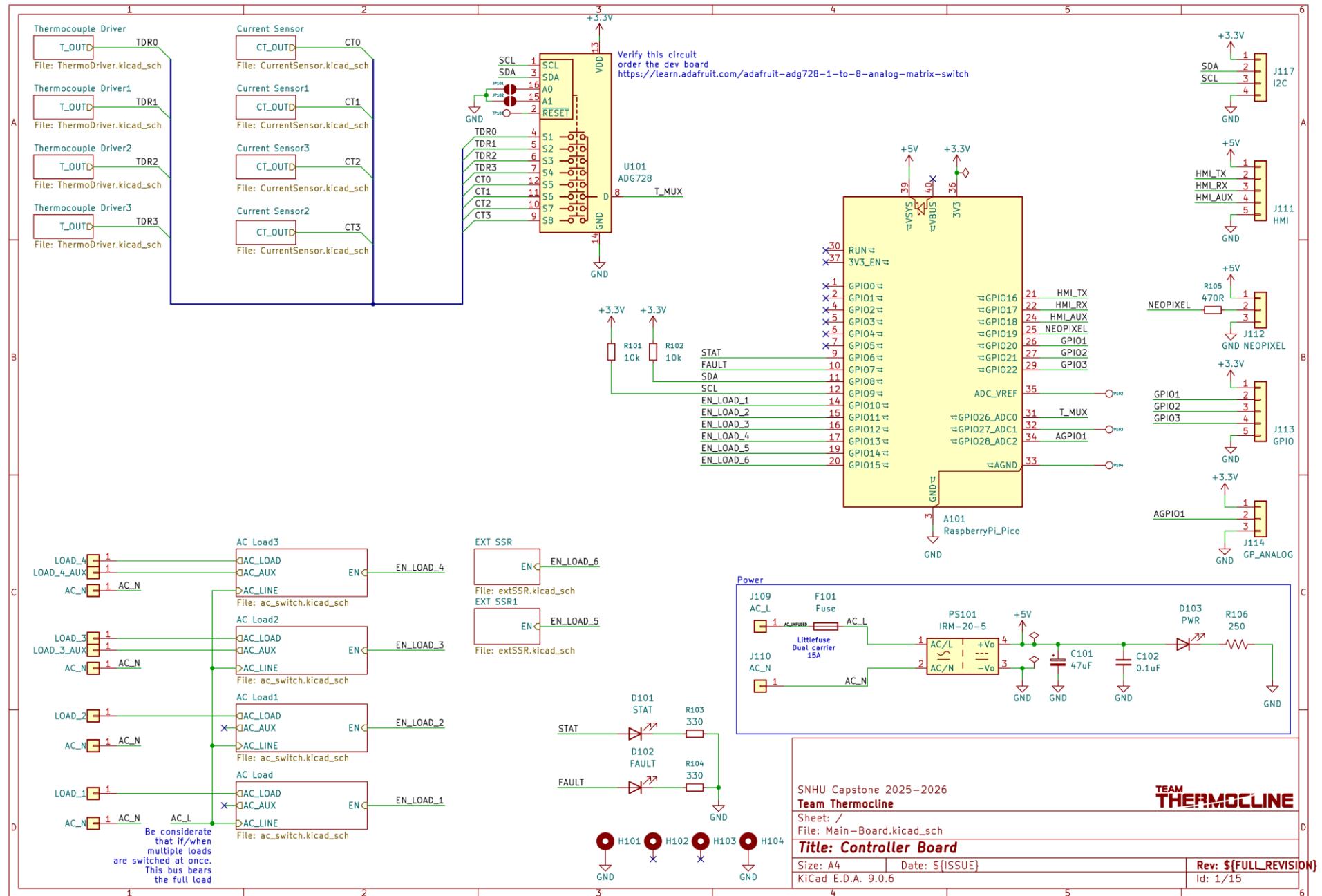
High level overview

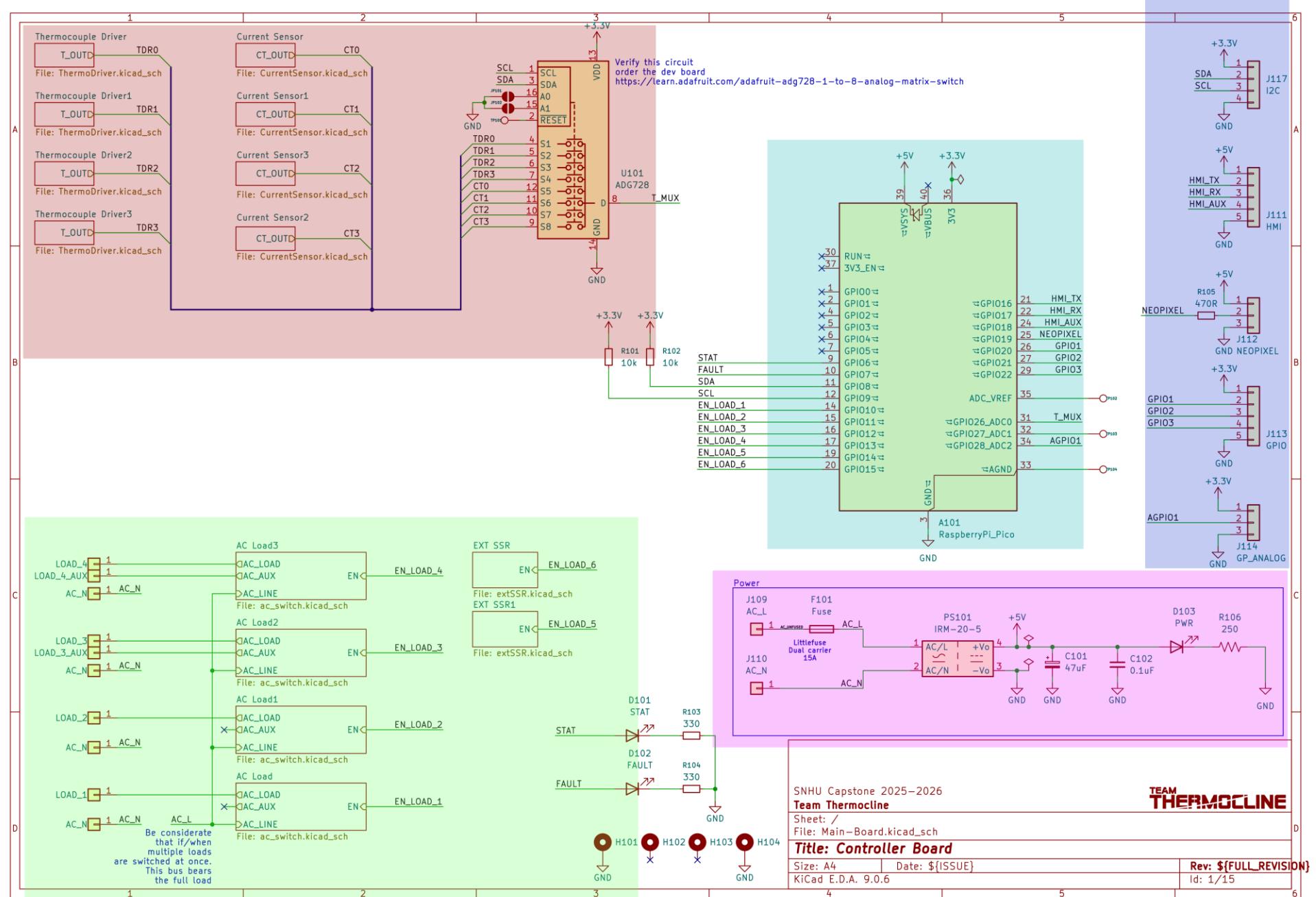
Driving Requirements:

- COM-03: The system shall adhere to UL 61010 for test and measurement equipment.

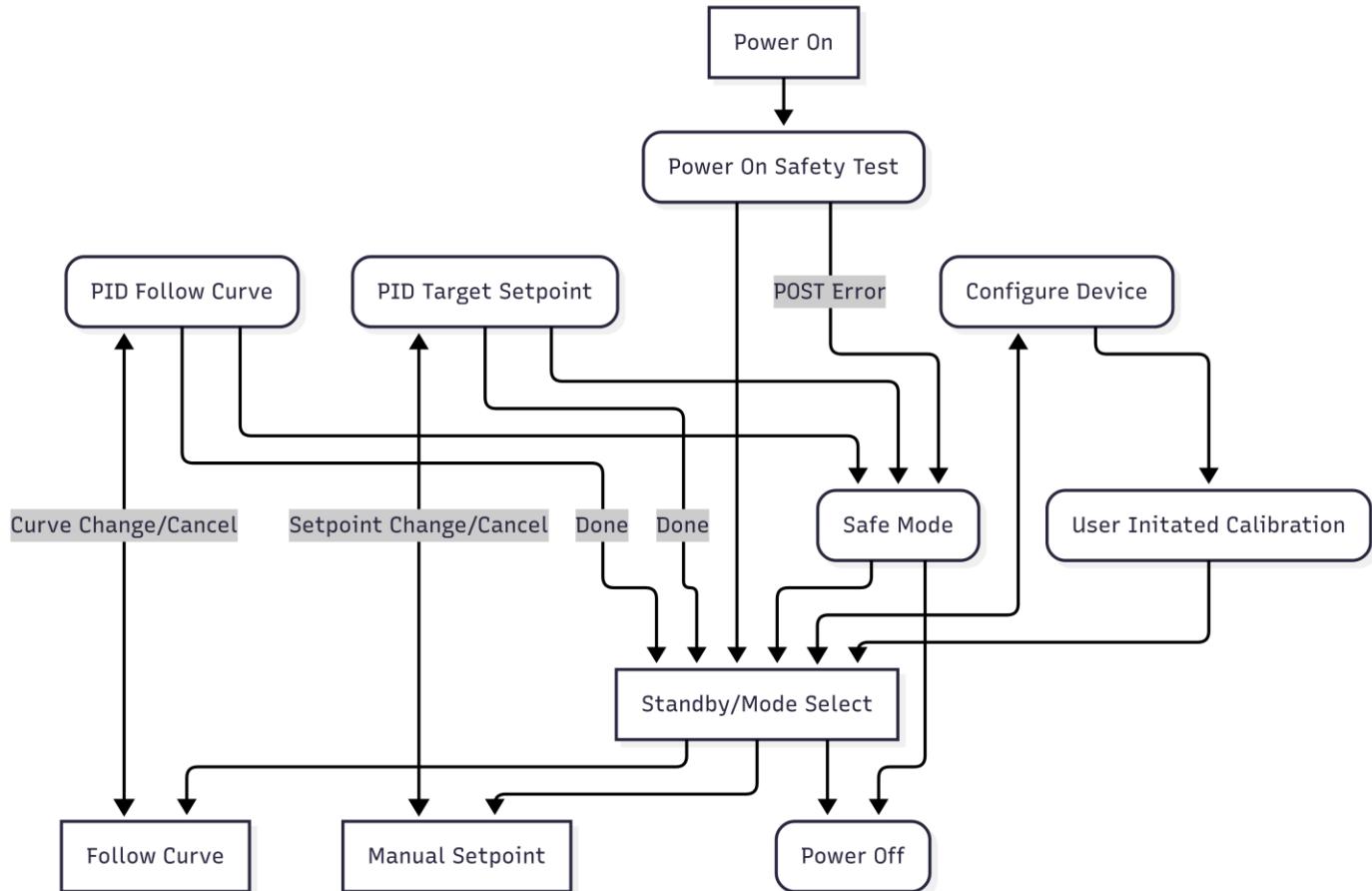


Mainboard PCB (current)





Subsystem Design: Control System



Driving Requirements

- CON-07: The system shall log humidity data.
- CON-08: The system shall log faults for safety measures.
- CON-09: The system shall have a "shutdown" state.
- CON-10: The system shall have a "standby" mode.
- CON-11: The system shall have a normal operating "start" mode.
- CON-12: The system shall allow for manual switching between modes.
- SAF-05: The system shall have a "safe" state.



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Subsystem Design: Control System

```
17  /**
18   * @brief Queueable command structure
19   *
20   * You can use almost anything in a FreeRTOS queue,
21   * but this structure pretty much has everything we want.
22   * Feel free to edit.
23   * @author Joe
24   */
25  struct Command {
26      Interface interface;
27      char command[64]; // Command name/type
28      char data[512];   // JSON data/arguments as string
29
30      /**
31       * @brief Default constructor - initializes with empty values
32       */
33      Command() : interface(Interface::UNKNOWN) {
34          command[0] = '\0';
35          data[0] = '\0';
36      }
37  }
```

- RTOS boilerplate and command structure is laid out.
- Communication already works solidly with the website
<https://team-thermocline.github.io/>
- Connection to the HMI is the same language and format

Subsystem Design: Safety

- **SAF-01:** The internal surfaces shall be safe for electronics according to ASTM D3874-20
- **SAF-02:** The system external surfaces shall not exceed the safe-touch temperature of 50 C according to ASTM C1055
- **SAF-03:** The System shall be able to operate in normal environment (external) conditions of 21 C
- **SAF-04:** The system shall include a safety measure if temperature range & tolerance is exceeded



Safety Warning Light

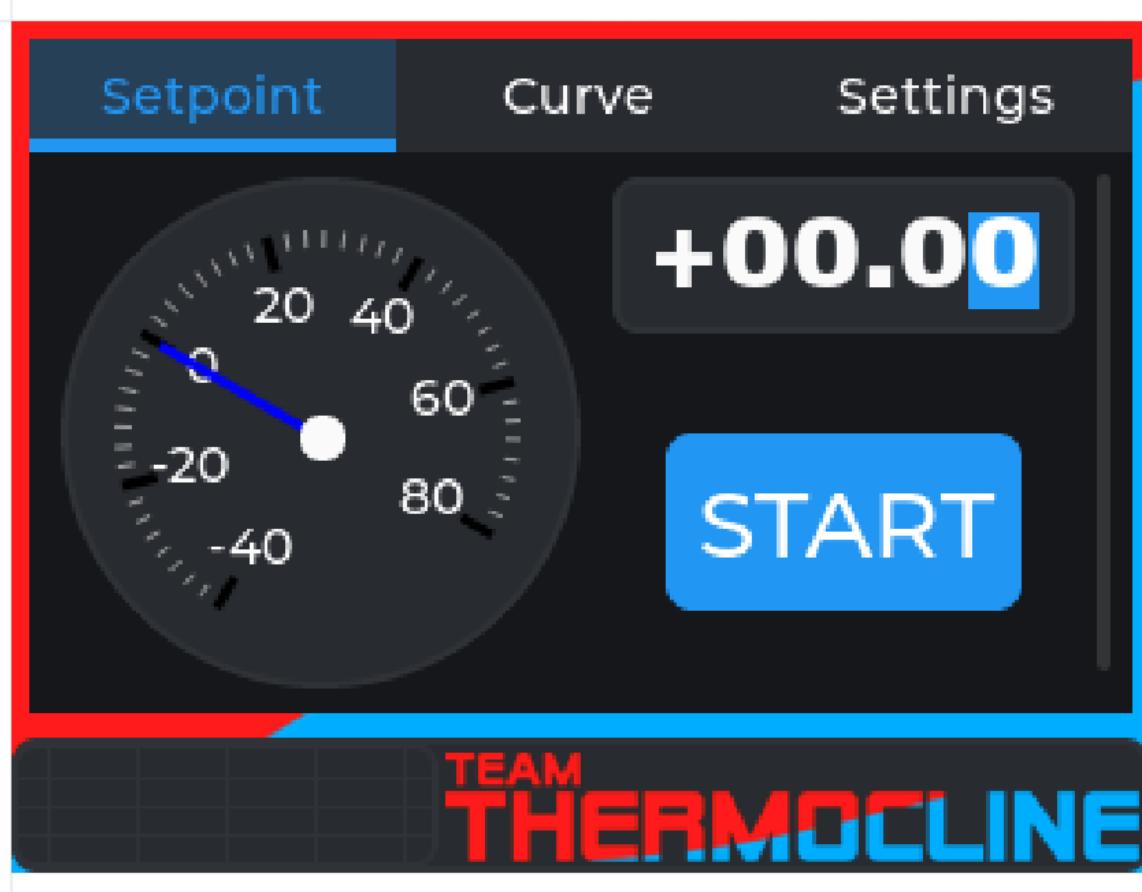
Subsystem Design: Control System

Control System HMI

The HMI (Human Machine Interface) is written in C with LVGL as the graphics backend.

Communicates to the MCU with the same JSON based communication language.

Meets requirements for presenting the state of the machine to the user as well as allowing user input.



UI in LVGL



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Budget:

Overall Budget

#	Category	Original Budget (\$)	Spent (\$)	Balance (\$)
1	Materials	600	42.69	557.31
2	Hardware	600	87.72	512.28
3	Software	600	50	550
4	Management Reserve	600	0	600
5	Other	600	503	97
Total (\$):		3000	683.41	2316.59

We have spent 23% of our total budget.

Itemized Expenses

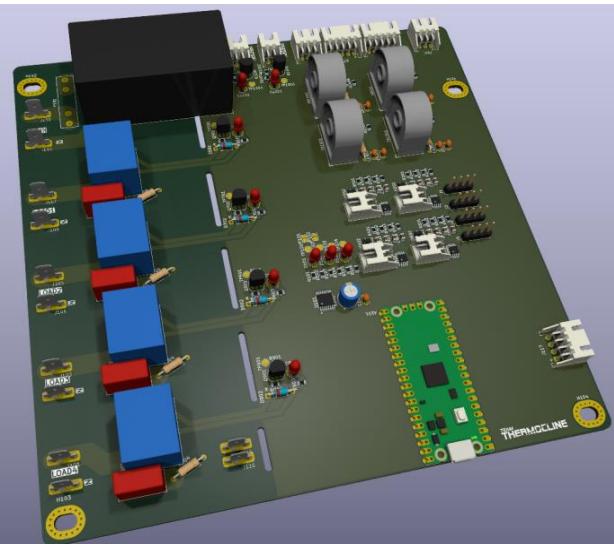
Item	% of Budget	Price
PCB	1%	\$ 35.00
Compressor	0%	\$ -
SendCutSend	1%	\$ 30.00
HMI Screen	2%	\$ 50.00
Recovery Pump	13%	\$ 388.00
Manifold Gauge	2%	\$ 49.00
Reciver Cylinder	2%	\$ 66.00
Resistive Heater Core	1%	\$ 29.55
9" Fan	1%	\$ 23.17
Polycarb Square Sheet	0%	\$ 12.69
Total Purchases	23%	\$ 683.41
Total Budget	100%	3000
Total Budget Left	77%	\$ 2,316.59



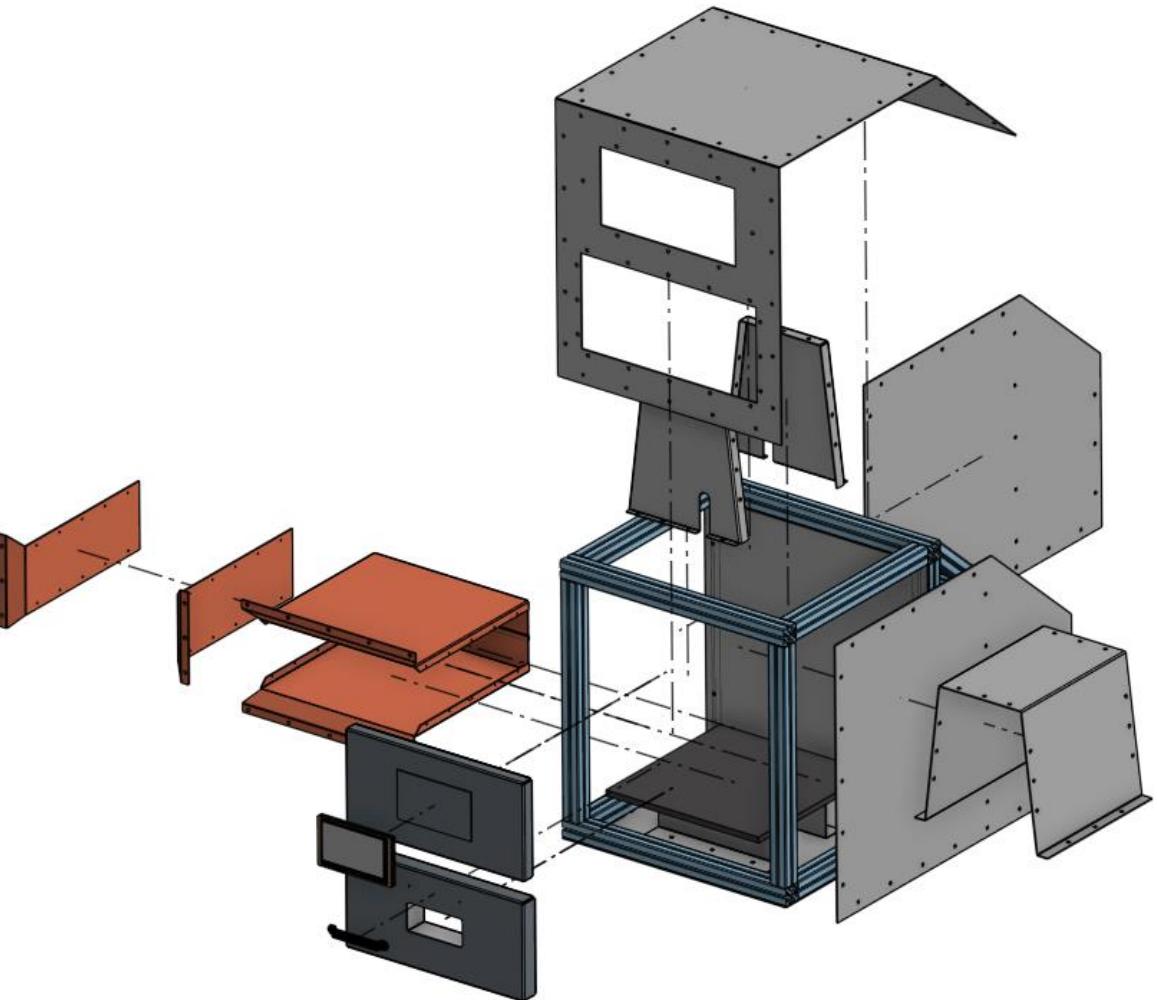


Open Design Items

- Chassis
- Shocks/Vibration Dampening
- Pre-Final Sheet Metal (Laser Cutter)
- Fans and Cooling (✓)
- Recovery and Logistics (✓)



Mainboard



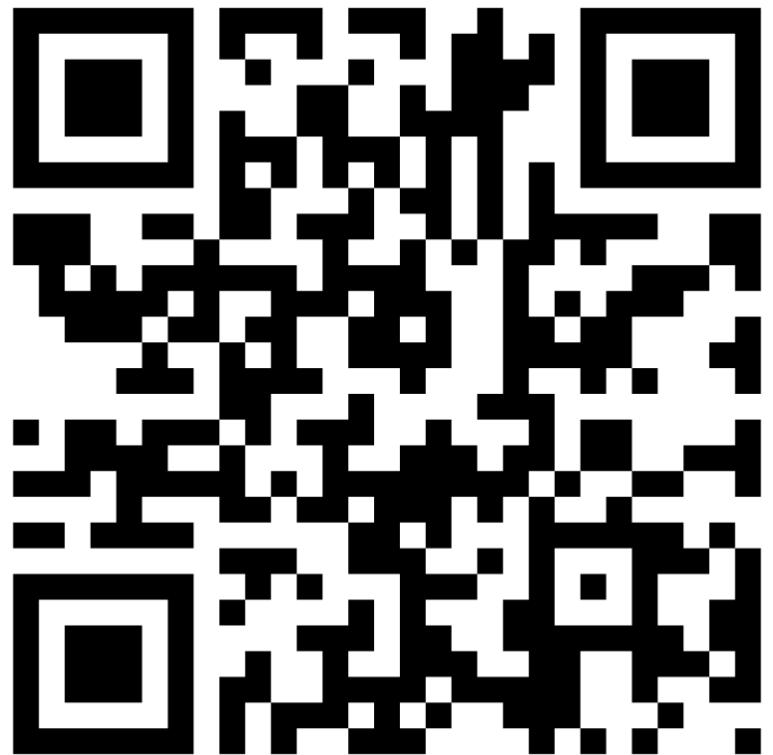
Sheet Metal and Extrusion



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Data Acceptance Package

Deliverable	Status
CAD assembly & parts	
Drawings as PDF	
Assembly drawing as PDF	
Schematics	
PCB Layout (if relevant)	
Flowchart	
Pseudocode or preliminary code	
User interface design	
Final Report	

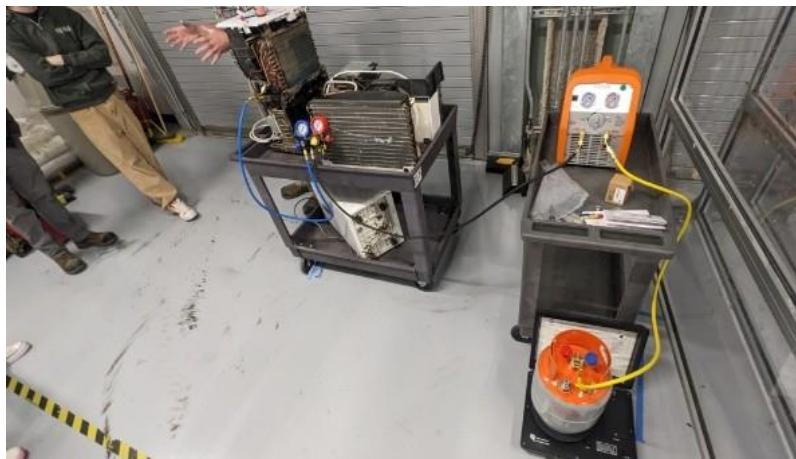


Questions?



BACKUP SLIDES

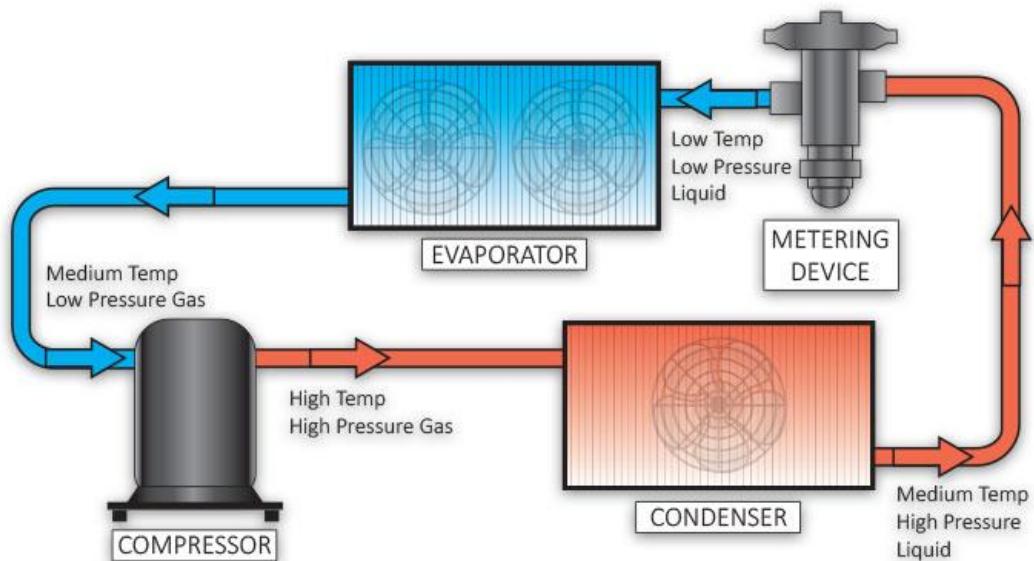
Refrigerant Recovery



- Refrigerant recovered and removed. Allowing safe work and CAD modeling of parts.

Control System Exploration

- Time Proportional PID (Duty Cycle PID)
- Why cant you use normal PID?
 - You can for **heat** but you cannot for cooling.
 - The reason is the head start problem. At max load, especially around where our system will operate at the -40 mark. The system head pressure ahead of the compressor will be **VERY** high as refrigerant struggles to boil in the cold environment behind. This is a common problem in HVAC where we cannot simply fast cycle. And must account for a **minimum off-time** to allow the pressure to drop.
- Will This control method allow for our fine (3deg) control?
 - Sorta, Kinda. When we charge the system, ideally, we use enough fluid to enable the cold side to **just boil** at our min temperature. This will leave us a **little overcharged at higher temperatures**. But will allow us greater, smoother control down low. And with our capillary metering, enable near cryo temperatures. Its complex to characterize but we may have a band especially at the **-5 to -10** mark where our minimum off time and desired cycle time are at odds.



Hi Jason,

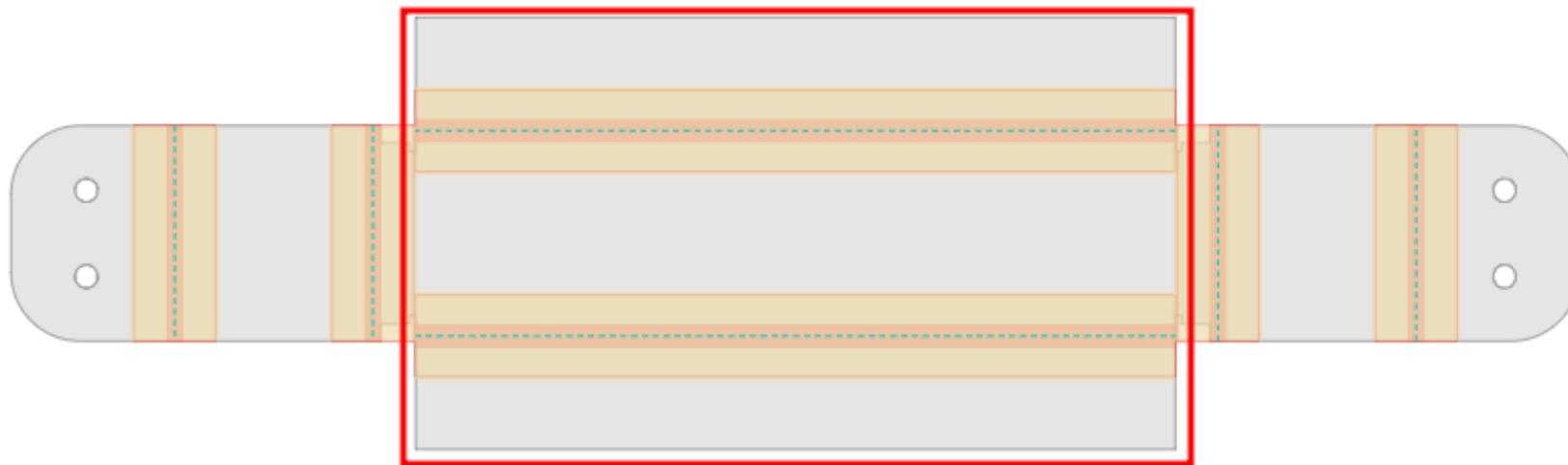
Thank you so much for your order! During our preproduction design checks, we noticed an issue that forced us to place **your order on hold**.

There are some limitations to what we can form in a "U" channel configuration before the bent part collides with the bending equipment. To avoid these collisions, we need the base-to-flange ratio to be at least 2:1.



2:1 RATIO FOR SHEET METAL

[Tweaks_Replacement_Body.step](#)



We have your order on hold for now. Would you like to revise your design, or have the bending operation removed and the part shipped flat?

$$L_{\text{floor}} := 13 \text{ in} \quad H_{\text{wall}} := 6 \text{ in}$$

$$A_{\text{internal}} := 2 \cdot L_{\text{floor}}^2 + 4 \cdot (L_{\text{floor}} \cdot H_{\text{wall}}) = 0.4194 \text{ m}^2$$

$$t_{\text{start}} := 20 \text{ } ^\circ\text{C} \quad t_{\text{end}} := (-40) \text{ } ^\circ\text{C}$$

$$\Delta_t := t_{\text{end}} - t_{\text{start}} = -60 \text{ K}$$

$$U := 5 \frac{\text{W}}{\frac{2}{m} \text{ K}}$$

Overall heat transfer estimate

$$Q_{\text{cond}} := U \cdot A_{\text{internal}} \cdot \Delta_t = -429.2686 \frac{\text{BTU}}{\text{hr}}$$

BTU just to maintain the condition.

Not accounting for the density of air or anything just assuming contents of box and aluminum walls dominate.

$$c_{p_aluminum} := 0.9 \frac{kJ}{kg \ K} \quad m_{aluminum} := 1 \ kg$$

$$Q_{pull} := m_{aluminum} \cdot c_{p_aluminum} \cdot \Delta_t = -51.1821 \text{ BTU}$$

$$t_{time_to_cool} := 30 \text{ min}$$

$$Q_{total} := Q_{cond} + \frac{Q_{pull}}{t_{time_to_cool}} = -531.6328 \frac{BTU}{hr}$$

SERIAL CONSOLE

Connect to your thermal chamber controller via serial port.

⚠ Browser Compatibility: This tool works best in Chrome/Edge. Firefox support varies by version.

BAUD RATE: AUTO-CONNECT ON PAGE LOAD

Enter command...



Requirements Database- Design

1.1	The system shall accomodate a 12x12" PCB as device to be tested.	Demonstration
1.1.1	The system shall have external base dimensions of maximum 30x30 inches.	Measure
1.2	The system shall include insulation designed for external safety according to ASTM C1055.	Inspection
1.2.1	The chamber opening(s) shall include proper thermal sealing.	Inspection
1.2.2	The internal thermal control components shall include proper thermal sealing.	Inspection
1.3	The system's design shall be safe for continual operation.	Measure
1.3.1	The internal surfaces shall be safe for electronics.	Analysis
1.3.2	The system external surfaces shall not exceed the safe-touch temperature of 50°C according to ASTM C1055.	Analysis
1.3.3	The system shall be able to operate in normal environmental (external) conditions of 21°C.	Demonstration

Requirements Database- System

2.1	The system shall include a port to allow electrical cables to enter and leave for stimulus and measurement of the PCB.	Inspection
2.1.1	The PCB shall be operable while temperature is controlled.	Measure
2.2	The system shall comply with electrical grounding requirements.	Inspection
2.3	The system shall be able to operate on a standard wall-outlet power of 120V (AC).	Demonstration
2.4	The system will comply with appropriate NEC and UL rules governing powered and plug in devices.	Inspection
2.4.1	System will adhere to NEC rules on grounding.	Inspection
2.4.2	System will adhere to NEC rules on appropriate fuses and load wire sizes.	Inspection
2.4.3	System will adhere to UL 61010 for test and measurement equipment.	Inspection

Requirements Database- Functional

3.1	The system shall monitor temperature inside the chamber.	Demonstration
3.1.1	The sensors shall be properly rated to withstand internal environmental conditions.	Analysis
3.2	The system shall control temperature inside the chamber.	Demonstration
3.2.1	The system shall cover <i>commercial</i> temperature range (0°C - 70°C). [Optional]: cover <i>industrial</i> temperature range (-40°C - 85°C).	Measure
3.2.2	The system shall allow local temperature setpoint control.	Test
3.2.3	The system shall allow remote temperature setpoint control.	Test
3.2.4	The system shall maintain a toleranced temperature at $\pm 3^{\circ}\text{C}$ of setpoint.	Measure
3.2.5	The system shall prohibit thermal control when the chamber door is open.	Demonstration
3.2.6	The system shall prohibit thermal control when a user is handling the PCB.	Demonstration
3.2.7	The system shall include a safety measure if temperature range & tolerance is exceeded.	Demonstration
3.3	The system shall remain within a specified humidity range (0% - 90%).	Measure
3.4	The system shall provide data output.	Demonstration
3.4.1	The system shall support PC connection for datalogging.	Inspection
3.4.2	The system shall log temperature data.	Test
3.4.3	The system shall log humidity data.	Test
3.4.4	The system shall log faults for safety measures.	Measure
3.4.5	The system shall be capable of sweeping all temperature ranges within a 24-hr cycle.	Test

Requirements Database- Interface

		Inspection
4.1	The system shall include an HMI for the control system.	Demonstration
4.2	The system shall include separate operating/control modes.	Demonstration
4.2.1	The system shall have a "shutdown" state.	Demonstration
4.2.2	The system shall have a "standby" mode.	Demonstration
4.2.3	The system shall have a normal operating "start" mode.	Demonstration
4.2.4	The system shall have a "safe" state.	Demonstration
4.2.5	The system shall allow for manual switching between modes.	Demonstration

Risk Assessment - List

A	Asset	Mechanical Failure of Components (worn, broken)
B	Asset	Insufficient Dimensions for PCB testing (internal, external, cable port, chamber door)
C	Asset, Human Safety	Internal System is <u>Over</u> Temperature Range (fire, melting components)
D	Asset, Human Safety	Internal System is <u>Under</u> Temperature Range (freezed components)
E	Asset, Performance	System's Safety Measure Fails If Outside Temperature Range
F	Asset, Performance	Internal Heating/Cooling System <u>Can't Reach</u> upper/lower boundaries (poor components, inefficient controller)
G	Asset, Performance	Inconsistent Temperature Control (poorly designed microcontroller or interface)
H	Asset, Performance	Failure to Maintain Toleranced Setpoint ($\pm 3^\circ\text{C}$) (ineffective control system, poor insulation - internal & external)
I	Asset, Performance	Lack of Electronic Protection (excessive moisture buildup)
J	Cost	Spending Past Designated Budget for Equipment & Materials
K	Human Safety	Lack of Human Protection at Critical Temperature Ranges (burns)
L	Human Safety	System Fails to Meet Environmental/Engineering Codes
M	Human Safety	System Fails to Prohibit Temperature Control During Manual User Usage.
N	Human Safety, Performance	Chemical Leaking
O	Human Safety, Performance	Electrical Hazards (short circuits, improper connections)
P	Human Safety, Performance	System Fails to Operate Safely Under Normal Conditions
Q	Performance	Software/HMI Failure
R	Performance	Lack of Refrigerant Fluid in System
S	Performance	Controller not User Friendly (poor HMI design)
T	Performance	Sensor Reading Failure (miscalibration, component issue)
U	Performance	Improper Ventilation (pressure changes, fumes buildup)
V	Performance	Ineffective Insulation (poor materials or design)
W	Performance	Data Measuring, Collecting, and Logging Fail to Work Systematically
X	Performance	System Mode(s) Failures
Y	Schedule	Poor Scheduling for Fabricated Parts or Sourced Materials
Z	Schedule, Cost	Rework of Product (ineffective design from failed systems/components/materials)

Risk Assessment - Matrix

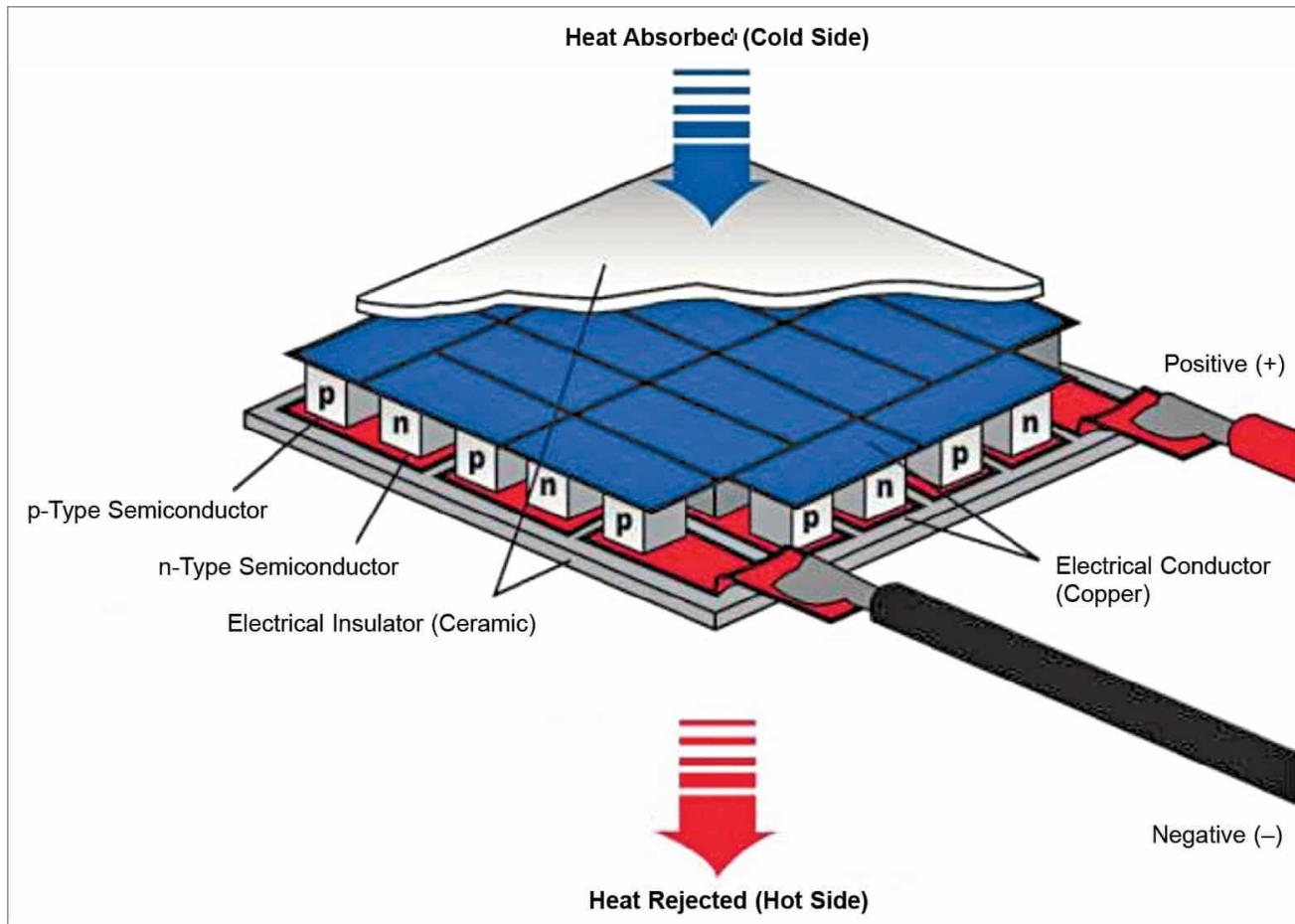
Consequence	5	B, L	A, E, P	K, M, O	Z	
	4		Y	N	I	Q, W
	3		F, G	T, U, X	V	
	2	R	J		C, D	H
	1	S				
		1	2	3	4	5
Likelihood						
Notes:	<p>Combined Risk Scores: 0-9 (Green) --> Minor 10-19 (Yellow) --> Moderate 20-29 (Red) --> Major</p>					

Peltier Analysis

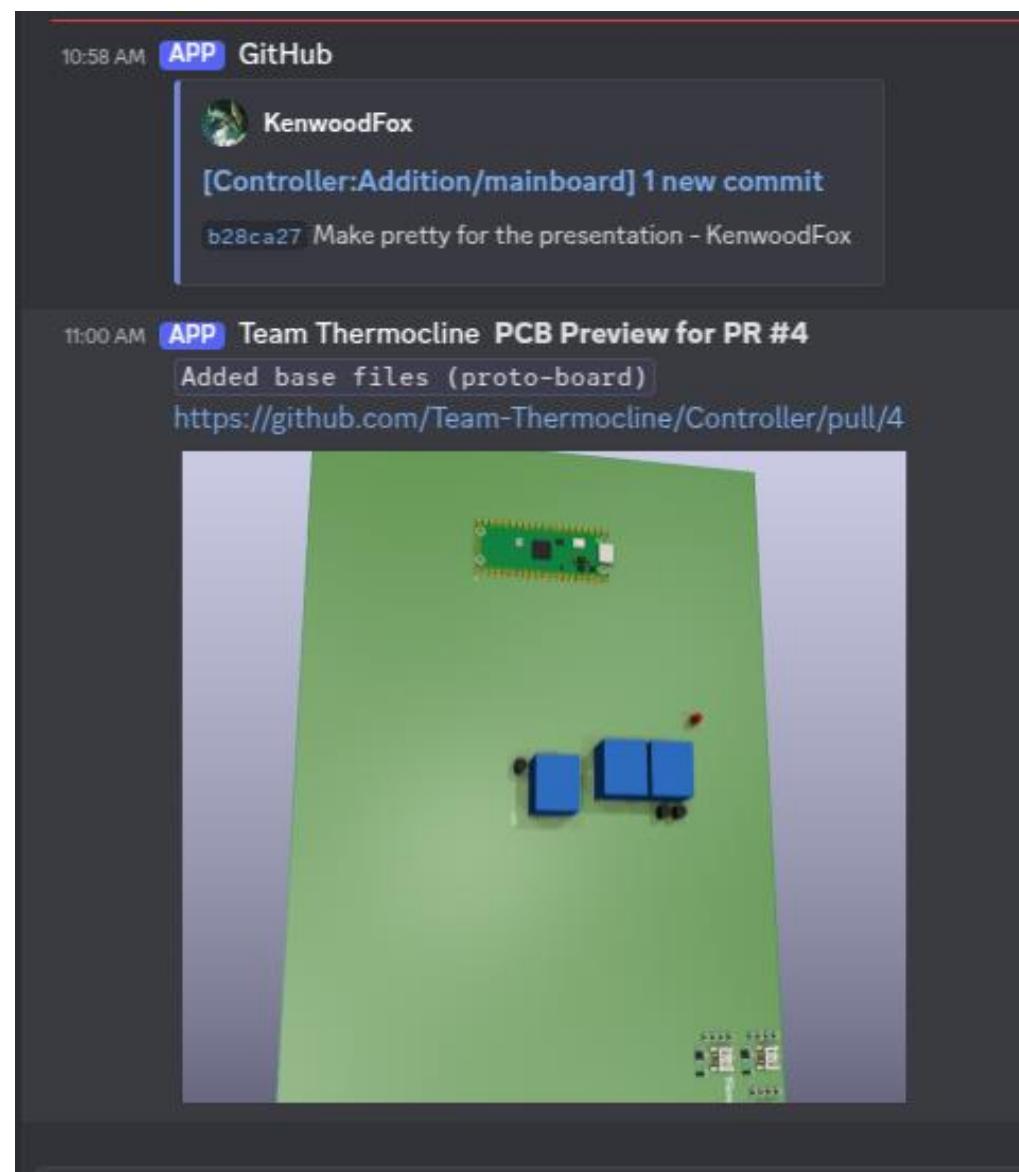
We explored using electric Peltier coolers. Which work by applying electrical current through a semiconductor, to move heat through a ceramic plate.

Our analysis found that a Peltier system that moves the thermal energy we expect to need, would require upwards of **400BTU/h to maintain temperature** and more than **500BTU/h** to change temperature at project requirement rates.

When weighed against our other avenues of heating and cooling we did not consider Peltier as a good fit for our design, specifically.



Sources on slides 28-29



Team-Thermocline / Controller ✓

Type to search

Code Issues 1 Pull requests 2 Actions Settings Releases 1

Actions New workflow

All workflows Showing runs from all workflows

Filter workflow runs

Help us improve GitHub Actions Tell us how to make GitHub Actions work better for you with three quick questions. Give feedback ×

69 workflow runs Event Status Branch Actor

Event	Status	Branch	Actor
Added base files (proto-board)	(Addition/mainboard)	16 minutes ago	32s
Added base files (proto-board)	(Addition/mainboard)	16 minutes ago	1m 38s
Added base files (proto-board)	(Addition/mainboard)	Today at 10:08 AM	32s
Added base files (proto-board)	(Addition/mainboard)	Today at 10:08 AM	1m 31s
Added base files (proto-board)	(Addition/mainboard)	Today at 9:48 AM	1m 18s
Added base files (proto-board)	(Addition/mainboard)	Today at 9:48 AM	35s

Attestations Runners Usage metrics Performance metrics

Actions All workflows Firmware Hardware Management Caches Attestations Runners Usage metrics Performance metrics



Alexandra Friebolein
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Jacob Morrisette
Chief Test Engineer
(M.E.)



Nik DiLullo
Chief Analyst
(E.E.)



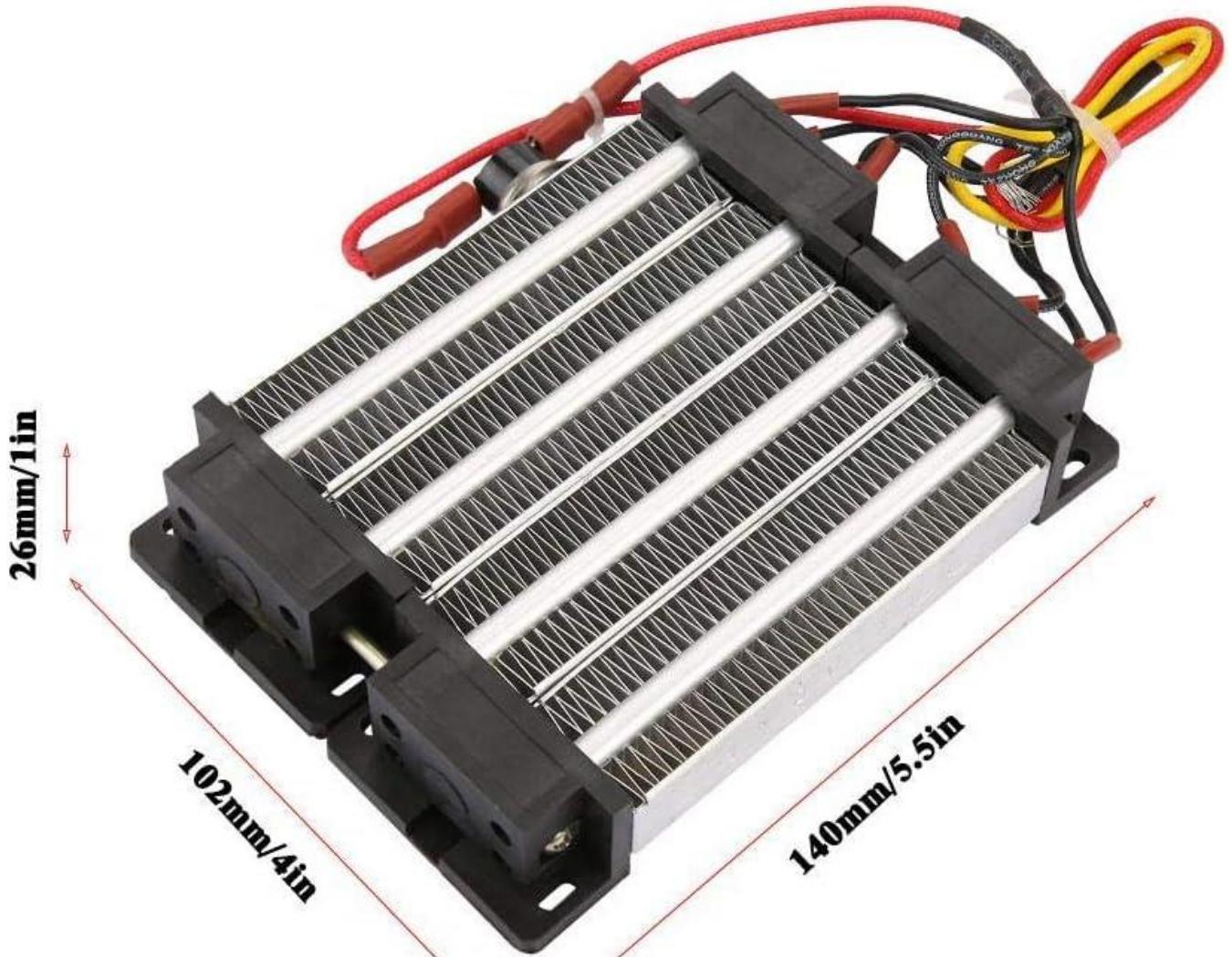
Joe Sedutto
Systems Engineer
(E.E.)



Alexia Hnatowicz
Project Engineer
(M.E.)

- Amazon heater
Sub \$50
Super easy to replace
Comes in every size we could want

Power from 800-1.2kw, easily in range



ORDER SX357091



To get your parts to you as quickly as possible,
your order may be fulfilled from multiple
SendCutSend locations.

PACKAGE[Show all tracking updates](#)

Nov 4, 4:16 AM ON THE WAY LEXINGTON, KY

**We have received your order and it is being processed**

OCTOBER 27, 3:13 PM

Your order is being reviewed

OCTOBER 27, 4:50 PM

Your parts are being produced

OCTOBER 28, 3:29 PM

Your parts are being deburred

NOVEMBER 2, 12:32 AM

Your parts are being bent

NOVEMBER 2, 3:23 AM

Your parts are undergoing quality inspection

NOVEMBER 2, 6:40 AM

Some of your parts have been shipped

NOVEMBER 2, 7:31 AM

Your parts are on their way

NOVEMBER 2, 1:22 PM



5052 H32 Aluminum (.063")
9.094" x 2.507"

[TRACK ON UPS](#)[PACKING SLIP 1](#)

Shipping to:
Jason Crowell
Southern New Hampshire University
2500 North River Road

[VIEW INVOICE](#)[CONTACT US](#)